



20V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max
001/	35mΩ @ V _{GS} = 10V	4.6A
20V	40mΩ @ V _{GS} = 4.5V	4.3A

Features and Benefits

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen- and Antimony-Free. "Green" Device (Note 3)

Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}), yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

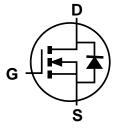
- Battery Charging
- Power Management Functions
- DC-DC Converters
- Portable Power Adaptors

Mechanical Data

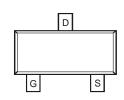
- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish—Matte Tin Annealed over Copper Lead-Frame.
 Solderable per MIL-STD-202, Method 208 (§3)
- Terminals Connections: See Diagram Below
- Weight: 0.009 grams (Approximate)



Top View



Internal Schematic



Top View

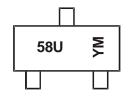
Ordering Information (Note 4)

Part Number	Case	Packaging
DMN2058U-7	SOT23	3,000/Tape & Reel
DMN2058U-13	SOT23	10.000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information



58U = Product Type Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: H = 2020) M or \overline{M} = Month (ex: 9 = September)

Date Code Key

Year	2016		~	2020		2021	2022 2023		2023	2024		2025
Code	D		~	Н		ı	J		K	L		М
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Characteristic	Symbol	Value	Units		
Drain-Source Voltage	V_{DSS}	20	V		
Gate-Source Voltage	V_{GSS}	±12	V		
Continuous Drain Current (Note 6) V _{GS} = 10V	I _D	4.6 3.7	А		
Maximum Body Diode Forward Current (Note 6)	I _S	1.2	Α		
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)		I _{DM}	24	Α

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Power Dissipation (Note 5)		P_{D}	0.74	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{ heta JA}$	172	°C/W	
Power Dissipation (Note 6)		P_{D}	1.13	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{ heta JA}$	111	°C/W
Operating and Storage Temperature Range		$T_{J_i} T_{STG}$	-55 to +150	°C

Electrical Characteristics (@ T_A = +25°C unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	20	_		V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 20V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)			•		•		
Gate Threshold Voltage	V _{GS(TH)}	0.4	0.6	1.2	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
		_	27	35		$V_{GS} = 10V, I_D = 6.0A$	
Static Drain-Source On-Resistance		_	30	40	mΩ	$V_{GS} = 4.5V, I_D = 5.0A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	37	60	11122	$V_{GS} = 2.5V, I_D = 4.0A$	
		_	49	91		$V_{GS} = 1.8V, I_D = 2.0A$	
Diode Forward Voltage	V _{SD}	_	0.7	1.2	V	$V_{GS} = 0V$, $I_S = 1A$	
DYNAMIC CHARACTERISTICS (Note 8)			•		•		
Input Capacitance	C _{ISS}	_	281	_		101/1/	
Output Capacitance	Coss	_	50	_	pF	$V_{DS} = 10V, V_{GS} = 0V$ f = 1.0MHz	
Reverse Transfer Capacitance	C _{RSS}	_	39	_		1 = 1.0IVII IZ	
Gate Resistance	R _G	_	3.1	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Q_{G}	_	3.6	_			
Total Gate Charge (V _{GS} = 10V)	Q _G	_	7.7	_	nC	101/1 004	
Gate-Source Charge	Q _{GS}	_	0.5	_	nc nc	$V_{DS} = 10V, I_D = 6.0A$	
Gate-Drain Charge	Q_{GD}	_	0.9	_			
Turn-On Delay Time	t _{D(ON)}	_	2.0	_			
Turn-On Rise Time	t _R	_	4.9	_		$V_{GS} = 4.5V, V_{DD} = 10V, R_G = 6\Omega,$	
Turn-Off Delay Time	t _{D(OFF)}	_	9.9		ns	$I_{D} = 6.0A$	
Turn-Off Fall Time	t _F	_	3.3	_			
Body Diode Reverse Recovery Time	t _{RR}	_	5.4	_	ns	$I_F = 6.0A$, di/dt = 100A/ μ s	
Body Diode Reverse Recovery Charge	Q _{RR}	_	0.7	_	nC	$I_F = 6.0A$, $di/dt = 100A/\mu s$	

Notes:

Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.

2.5

12

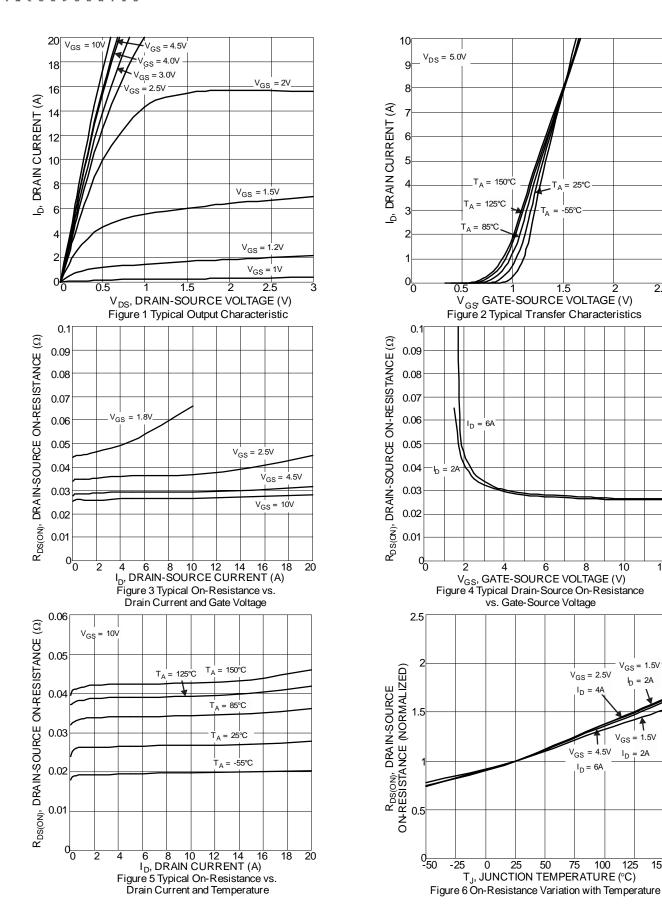
= 2A

 $V_{GS} = 1.5V$

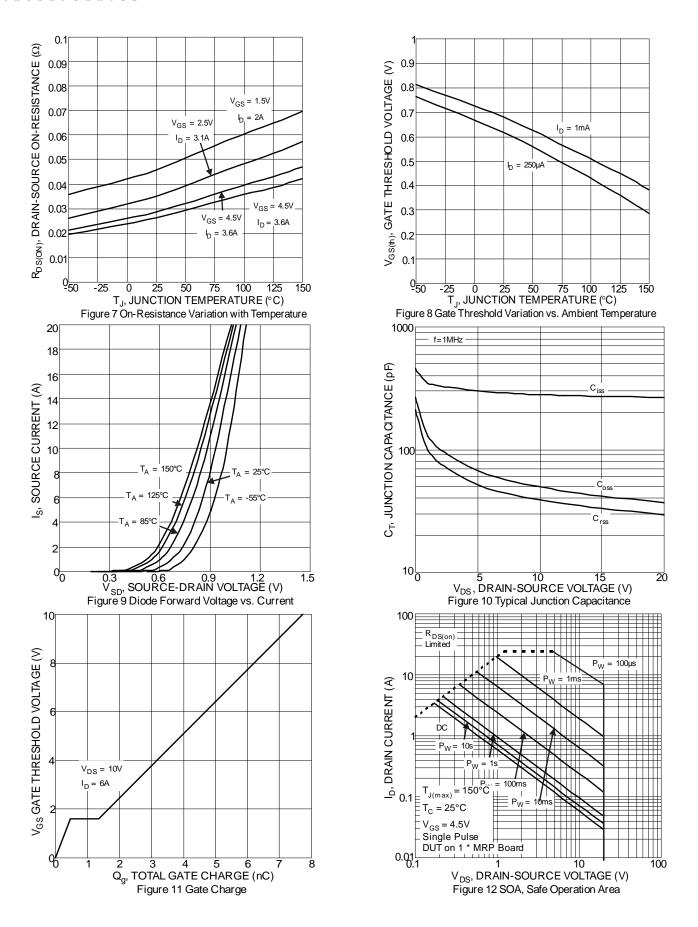
I_D = 2A

125

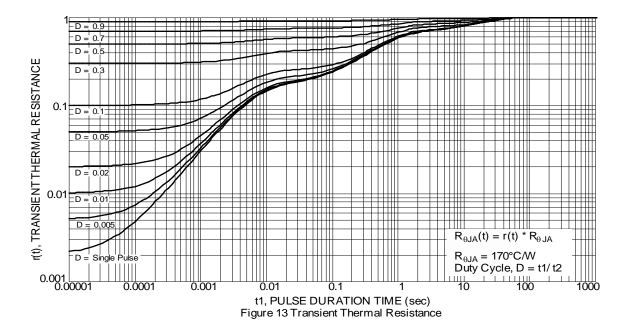










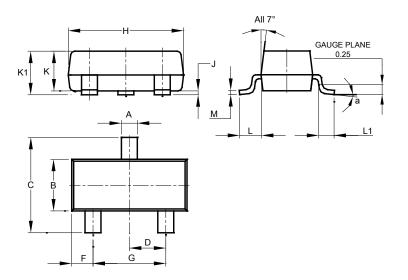




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23

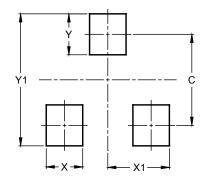


SOT23							
Dim	Min	Max	Тур				
Α	0.37	0.51	0.40				
В	1.20	1.40	1.30				
С	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
Н	2.80	3.00	2.90				
J	0.013	0.10	0.05				
K	0.890	1.00	0.975				
K1	K1 0.903		1.025				
L	0.45	0.61	0.55				
L1	0.25	0.55	0.40				
М	0.085	0.150	0.110				
а	a 0° 8°						
All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23



Dimensions	Value (in mm)
С	2.0
Х	0.8
X1	1.35
Y	0.9
Y1	29



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